509074738 03/12/2025

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 Assignment ID: PATI881273

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

#### **CONVEYING PARTY DATA**

Name	Execution Date
Atomica Corp.	11/18/2024

### **RECEIVING PARTY DATA**

Company Name:	Cenfire Corp
Street Address:	75 Robin Hill Road
City:	Goleta
State/Country:	CALIFORNIA
Postal Code:	93117

#### **PROPERTY NUMBERS Total: 10**

Property Type	Number
Patent Number:	7276991
Patent Number:	7528691
Patent Number:	7864006
Patent Number:	7893798
Patent Number:	8264307
Patent Number:	9953787
Patent Number:	11305982
Patent Number:	11594389
Patent Number:	10388468
Patent Number:	7233048

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 858-481-1883

**Email:** julianne@mlo-ip.com,docket@mlo-ip.com

Correspondent Name: Julianne Francis

Address Line 1: Attn: MLO

Address Line 2: 9920 Pacific Heights Blvd., Suite 150
Address Line 4: San Diego, CALIFORNIA 92121

NAME OF SUBMITTER: Mrs. JULIANNE FRANCIS

PATENT REEL: 070485 FRAME: 0105

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SIGNATURE: /Mrs. JULIANNE FRANCIS/				
<b>DATE SIGNED:</b> 03/12/2025				
Total Attachments: 3				
source=20250312_CENFA002_patent_assignment#page1.tiff				
source=20250312_CENFA002_patent_assignment#page2.tiff				
source=20250312 CENFA002 patent assignment#page3.tiff				

PATENT REEL: 070485 FRAME: 0106

#### INTELLECTUAL PROPERTY TRANSFER AGREEMENT

THIS INTELLECTUAL PROPERTY TRANSFER AGREEMENT ("IP Transfer Agreement") is made and entered into as of November 18, 2024, by and among Atomica Corp. ("Assignor"), and Cenfire Corp, ("Assignee"). All defined terms not otherwise defined herein shall have the meanings ascribed to such terms in the Assignment and Transfer Agreement, dated as of November 18, 2024, between Assignor and Assignee (the "Agreement").

#### RECITALS

WHEREAS, upon the terms and subject to the conditions of the Agreement, Assignor has agreed to transfer, convey and deliver to Assignee, and Assignee has agreed to acquire and accept from Assignor, all of Assignor's right, title and interest in and to the Cenfire Assets.

NOW, THEREFORE, in consideration of the covenants, promises and representations set forth herein and in the Agreement and for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the Parties hereto agree as follows:

- 1. <u>Assignment</u>. Assignor, hereby irrevocably assigns to Assignee, the entire right, title and interest for the United States of America and its territorial possessions and all foreign countries, in and to the patents and patent applications identified on <u>Schedule A</u> that are included in the Cenfire Assets ("<u>Listed Patents</u>"), together with (i) any patent and applications that claim priority from any of the Listed Patents, (ii) any patent and application that is a continuation, continuation in part (but only to the extent of any claims therein that are entitled to claim priority from any Listed Patent), divisional or reissue, of any Listed Patent or linked to any Listed Patent by a terminal disclaimer, (iii) any foreign counterpart of any such Listed Patent, and (iv) all rights corresponding thereto (together, the "<u>Patents</u>"). Assignee hereby accepts said assignment.
- 2. <u>Recordation and Further Actions</u>. Assignor does hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America or equivalent authority elsewhere in the world to record this assignment and to issue such Patent as shall be granted upon said applications based thereon to Assignee, its successors and assigns.
- 3. Counterparts. This IP Transfer Agreement may be executed in counterparts, each of which shall be deemed an original, but all of which together shall be deemed one and the same agreement. A signed copy of this IP Transfer Agreement delivered by facsimile, e-mail, or other means of electronic transmission shall be deemed to have the same legal effect as delivery of an original signed copy of this IP Transfer Agreement Assignment.
- 4. <u>Successors and Assigns</u>. This IP Transfer Agreement shall be binding upon and shall inure to the benefit of the Parties hereto and their respective successors and assigns.
- 5. <u>Governing Law</u>. This IP Transfer Agreement will be governed by, and construed in accordance with, the laws of the State of California, without reference to its conflict of laws principles. All disputes arising out of this Agreement will be heard exclusively in the courts of competent jurisdiction in Santa Clara County, California and both Parties waive the right to challenge that jurisdiction on any grounds.

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PATENT REEL: 070485 FRAME: 0107 **IN WITNESS WHEREOF**, the undersigned has executed this IP Transfer Agreement effective as of the date shown above.

## ATOMICA CORP.

By: Eldon klaassen

Name: Eldon Klaassen

Title: Managing Director

AGREED AND ACCEPTED:

**CENFIRE CORP** 

Suna Partokia

Name: Seena Partokia

Title: Chief Executive Officer

PATENT REEL: 070485 FRAME: 0108

# EXHIBIT A LISTED PATENTS

Patent Number	Title	Jurisdiction	Expiration
	MULTIPLE SWITCH MEMS STRUCTURE AND	U.S.	
7276991	METHOD OF MANUFACTURE		2026
	DUAL SUBSTRATE ELECTROSTATIC MEMS	U.S.	
	SWITCH WITH HERMETIC SEAL AND METHOD		
7528691	OF MANUFACTURE		2026
	MEMS PLATE SWITCH AND METHOD OF	U.S.	
7864006	MANUFACTURE		2028
	DUAL SUBSTRATE MEMS PLATE SWITCH AND	U.S.	
7893798	METHOD OF MANUFACTURE		2029
	DUAL SUBSTRATE MEMS PLATE SWITCH AND	U.S.	
8264307	METHOD OF MANUFACTURE		2027
	DUAL SUBSTRATE ELECTROSTATIC MEMS	U.S.	
	SWITCH WITH MULTIPLE HINGES AND		
9953787	METHOD OF MANUFACTURE		2036
	EIGHT SPRING DUAL SUBSTRATE MEMS	U.S.	
	PLATE SWITCH AND METHOD OF		
11305982	MANUFACTURE		2040
	MEMS DUAL SUBSTRATE SWITCH WITH	U.S.	
11594389	MAGNETIC ACTUATION		2038
10388468	CONTACT MATERIAL FOR MEMS DEVICES	U.S.	2036
	TRENCH PLATING PROCESS AND APPARATUS	U.S.	
7233048	FOR THROUGH HOLE VIAS		2025

PATENT REEL: 070485 FRAME: 0109

**RECORDED: 03/12/2025**